Plastic Packages for Integrated Circuits

Package Outline Drawing

V416.27x27

416 PLASTIC BALL GRID ARRAY PACKAGE (CAVITY DOWN)
Rev 0, 9/11

NOTES:

1. All dimensions are in millimeters.
   Dimensions in ( ) for Reference Only.

2. Terminal positions designation per JESD 95-1, SPP-010.

3. Pin #1 identifier can be chamfer, ink mark or metallized mark but located within the zone indicated.

4. Reflow ball diameter.

5. Compliant to JEDEC registered outline MS-034, variation AAF-1.